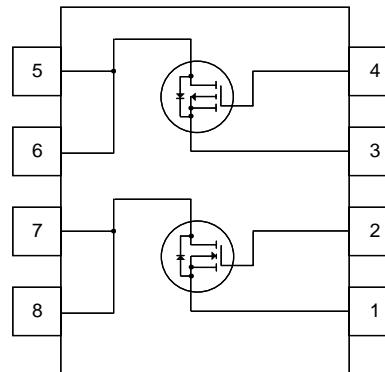
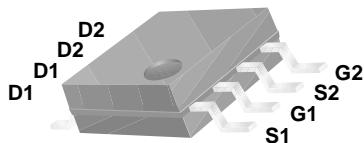


FQS4900**Dual N & P-Channel, Logic Level MOSFET****General Description**

These dual N and P-channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. This device is well suited for high interface in telephone sets.

Features

- N-Channel 1.3A, 60V, $R_{DS(on)} = 0.55 \Omega$ @ $V_{GS} = 10 V$
 $R_{DS(on)} = 0.65 \Omega$ @ $V_{GS} = 5 V$
- P-Channel -0.3A, -300V, $R_{DS(on)} = 15.5 \Omega$ @ $V_{GS} = -10 V$
 $R_{DS(on)} = 16 \Omega$ @ $V_{GS} = -5 V$
- Low gate charge (typical N-Channel 1.6 nC)
(typical P-Channel 3.6 nC)
- Fast switching
- Improved dv/dt capability

**Absolute Maximum Ratings** $T_A = 25^\circ C$ unless otherwise noted

Symbol	Parameter	N-Channel	P-Channel	Units	
V_{DSS}	Drain-Source Voltage	60	-300	V	
I_D	Drain Current - Continuous ($T_A = 25^\circ C$)	1.3	-0.3	A	
	- Continuous ($T_A = 70^\circ C$)	0.82	-0.19	A	
I_{DM}	Drain Current - Pulsed	(Note 1)	5.2	-1.2	A
V_{GSS}	Gate-Source Voltage		± 20	V	
dv/dt	Peak Diode Recovery dv/dt	(Note 2)	7.0	4.5	V/ns
P_D	Power Dissipation ($T_A = 25^\circ C$)		2.0	W	
	($T_A = 70^\circ C$)		1.3	W	
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +150	°C	

Thermal Characteristics

Symbol	Parameter	Typ	Max	Units
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	--	62.5	°C/W

Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Type	Min	Typ	Max	Units	
Off Characteristics								
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}} = 0 \text{ V}, I_D = 250 \mu\text{A}$ $V_{\text{GS}} = 0 \text{ V}, I_D = -250 \mu\text{A}$	N-Ch P-Ch	60 -300	-- --	-- --	V	
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}} = 60 \text{ V}, V_{\text{GS}} = 0 \text{ V}$	N-Ch	--	--	1	μA	
		$V_{\text{DS}} = 48 \text{ V}, T_C = 55^\circ\text{C}$		--	--	10	μA	
		$V_{\text{DS}} = -300 \text{ V}, V_{\text{GS}} = 0 \text{ V}$	P-Ch	--	--	-1	μA	
		$V_{\text{DS}} = -240 \text{ V}, T_C = 55^\circ\text{C}$		--	--	-10	μA	
I_{GSSF}	Gate-Body Leakage Current, Forward	$V_{\text{GS}} = 20 \text{ V}, V_{\text{DS}} = 0 \text{ V}$	All	--	--	100	nA	
I_{GSSR}	Gate-Body Leakage Current, Reverse	$V_{\text{GS}} = -20 \text{ V}, V_{\text{DS}} = 0 \text{ V}$	All	--	--	-100	nA	
On Characteristics								
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}} = 4 \text{ V}, I_D = 20 \text{ mA}$	N-Ch	1.0	--	1.95	V	
		$V_{\text{DS}} = 4 \text{ V}, I_D = -20 \text{ mA}$	P-Ch	-1.0	--	-1.95	V	
$R_{\text{DS(on)}}$	Static Drain-Source On-Resistance	$V_{\text{GS}} = 10 \text{ V}, I_D = 0.65 \text{ A}$	N-Ch	--	0.39	0.55	Ω	
		$V_{\text{GS}} = 5 \text{ V}, I_D = 0.65 \text{ A}$		--	0.46	0.65	Ω	
		$V_{\text{GS}} = -10 \text{ V}, I_D = -0.15 \text{ A}$	P-CH	--	11.2	15.5	Ω	
		$V_{\text{GS}} = -5 \text{ V}, I_D = -0.15 \text{ A}$		--	11.4	16	Ω	
g_{FS}	Forward Transconductance	$V_{\text{DS}} = 10 \text{ V}, I_D = 0.65 \text{ A}$	N-CH	--	1.7	--	S	
		$V_{\text{DS}} = -10 \text{ V}, I_D = -0.15 \text{ A}$	P-CH	--	0.6	--	S	
Switching Characteristics								
$t_{\text{d(on)}}$	Turn-On Delay Time	N-Channel $V_{\text{DD}} = 30 \text{ V}, I_D = 1.3 \text{ A}, R_G = 25 \Omega$	N-Ch	--	5.7	21	ns	
			P-Ch	--	10	30	ns	
t_r	Turn-On Rise Time		N-Ch	--	21	50	ns	
			P-Ch	--	25	60	ns	
$t_{\text{d(off)}}$	Turn-Off Delay Time	P-Channel $V_{\text{DD}} = -150 \text{ V}, I_D = -0.3 \text{ A}, R_G = 25 \Omega$	N-Ch	--	11	32	ns	
			P-Ch	--	35	80	ns	
t_f	Turn-Off Fall Time		N-Ch	--	17	45	ns	
			P-Ch	--	47	105	ns	
Q_g	Total Gate Charge	N-Channel $V_{\text{DS}} = 48 \text{ V}, I_D = 1.3 \text{ A}, V_{\text{GS}} = 5 \text{ V}$	N-Ch	--	1.6	2.1	nc	
Q_{gs}	Gate-Source Charge		P-Ch	--	3.6	4.7	nc	
Q_{gd}	Gate-Drain Charge		N-Ch	--	0.28	--	nc	
			P-Ch	--	0.42	--	nc	
V_{DS}	Drain-Source Diode Forward Voltage	$V_{\text{GS}} = 0 \text{ V}, I_S = 1.3 \text{ A}$	N-Ch	--	0.82	--	nc	
		$V_{\text{GS}} = 0 \text{ V}, I_S = -0.3 \text{ A}$	P-Ch	--	2.1	--	nc	
Drain-Source Diode Characteristics and Maximum Ratings								
I_S	Maximum Continuous Drain-Source Diode Forward Current	$V_{\text{GS}} = 0 \text{ V}, I_S = 1.3 \text{ A}$ $V_{\text{GS}} = 0 \text{ V}, I_S = -0.3 \text{ A}$	N-Ch	--	--	1.3	A	
			P-Ch	--	--	-0.3	A	
V_{SD}	Drain-Source Diode Forward Voltage	$V_{\text{GS}} = 0 \text{ V}, I_S = 1.3 \text{ A}$	N-Ch	--	--	1.5	V	
		$V_{\text{GS}} = 0 \text{ V}, I_S = -0.3 \text{ A}$	P-Ch	--	--	-4.0	V	
Notes:								
1. Repetitive Rating : Pulse width limited by maximum junction temperature								
3. Pulse Test : Pulse width $\leq 300\mu\text{s}$, Duty cycle $\leq 2\%$								
4. Essentially independent of operating temperature								

Typical Characteristics : N-Channel

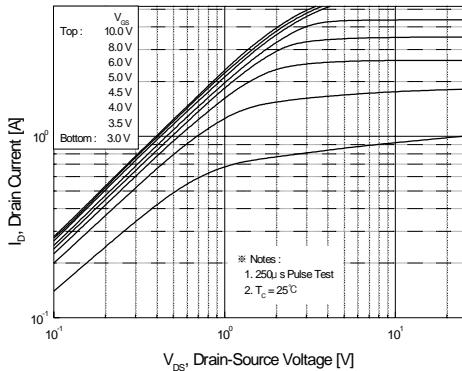


Figure 1. On-Region Characteristics

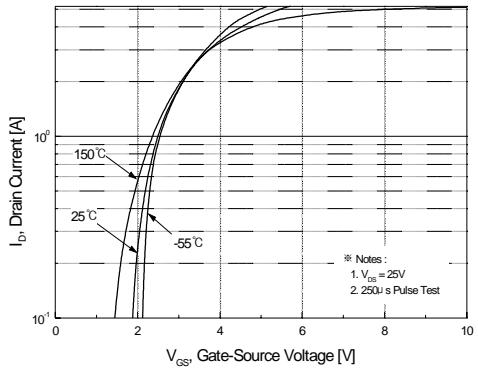


Figure 2. Transfer Characteristics

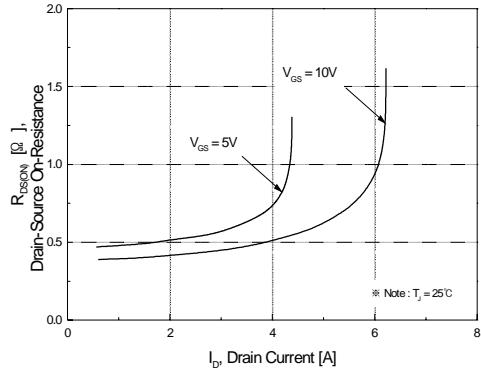


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

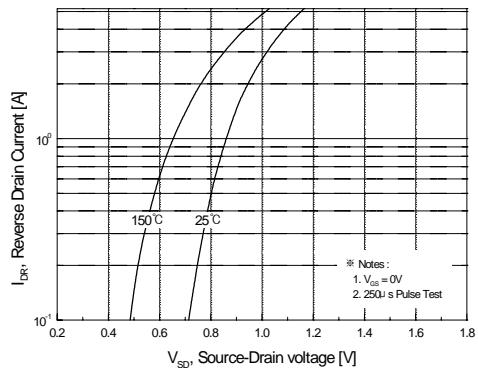


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

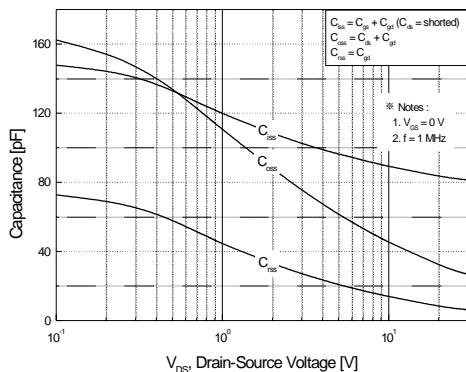


Figure 5. Capacitance Characteristics

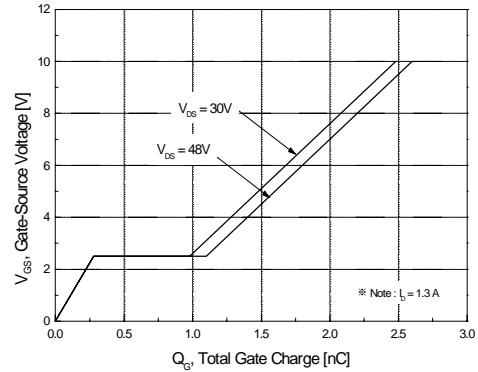
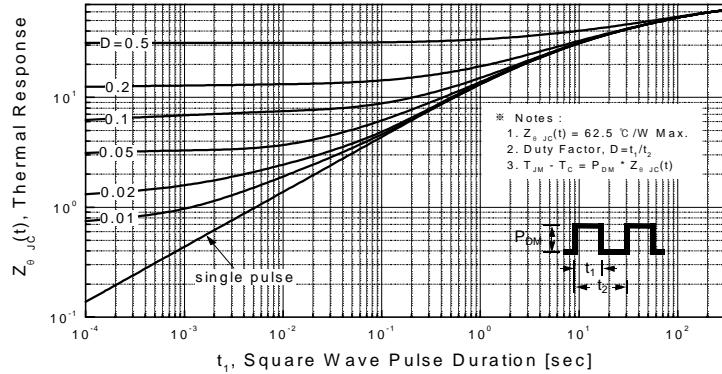
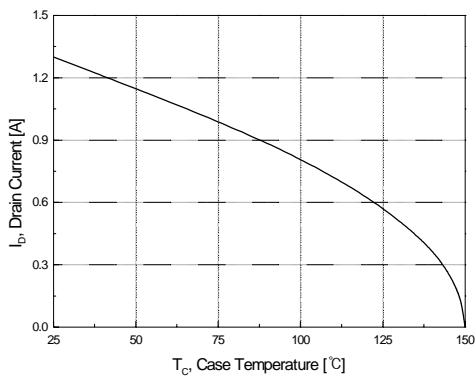
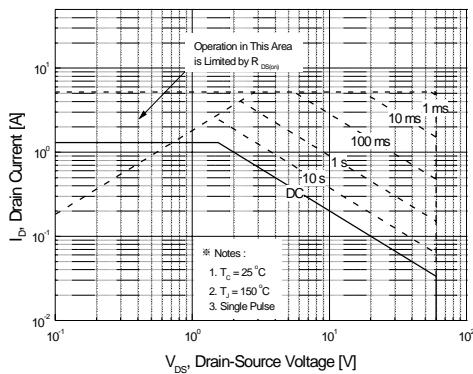
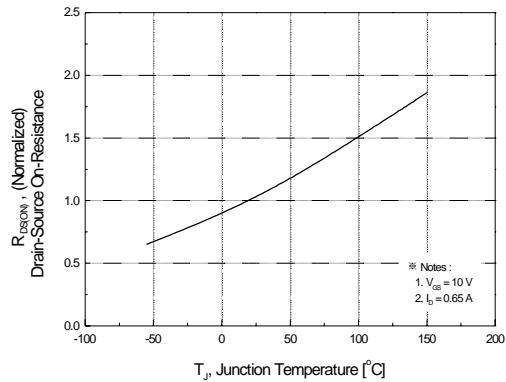
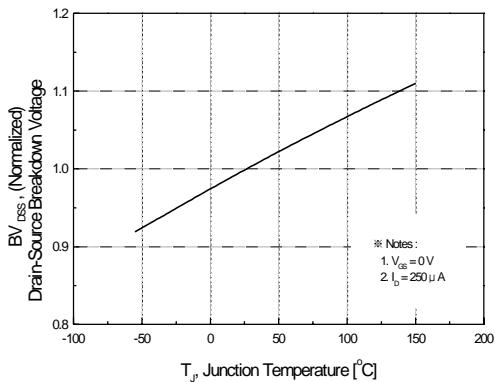


Figure 6. Gate Charge Characteristics

Typical Characteristics : N-Channel (Continued)



Typical Characteristics : P-Channel (Continued)

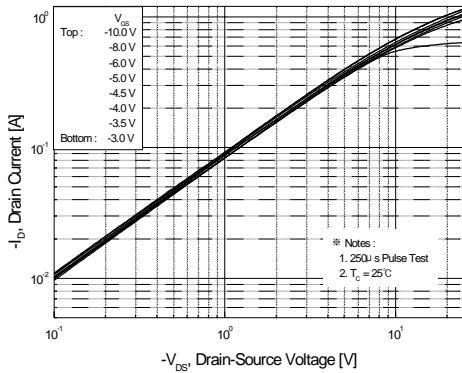


Figure 1. On-Region Characteristics

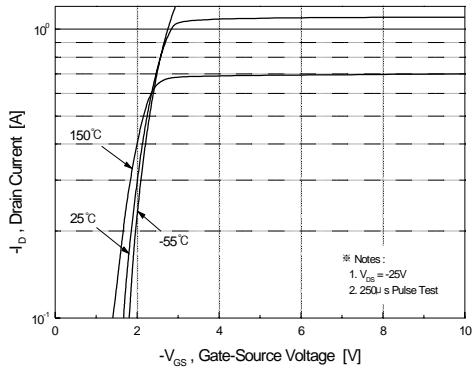


Figure 2. Transfer Characteristics

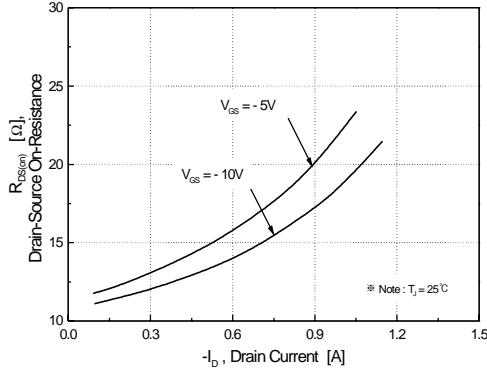


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

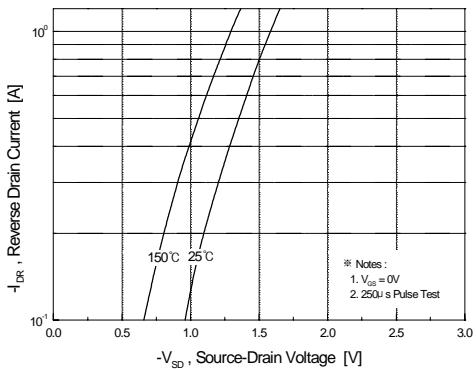


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

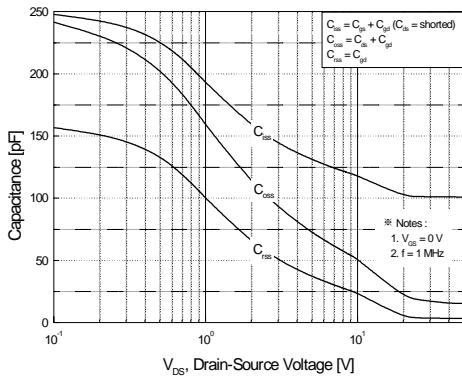


Figure 5. Capacitance Characteristics

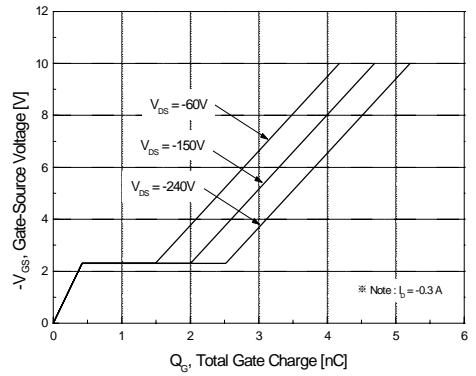
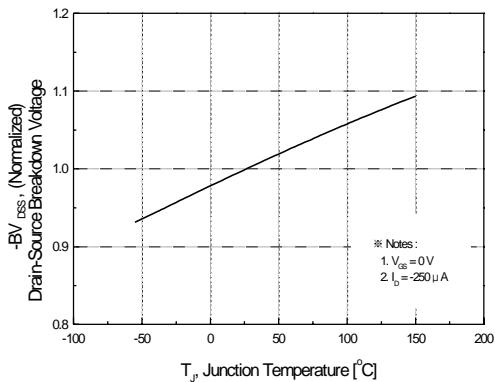
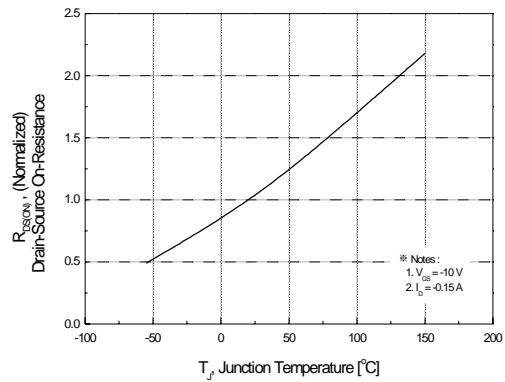


Figure 6. Gate Charge Characteristics

Typical Characteristics : P-Channel (Continued)



**Figure 7. Breakdown Voltage Variation
vs. Temperature**



**Figure 8. On-Resistance Variation
vs. Temperature**

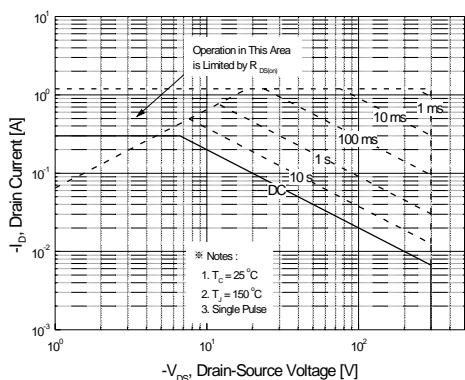
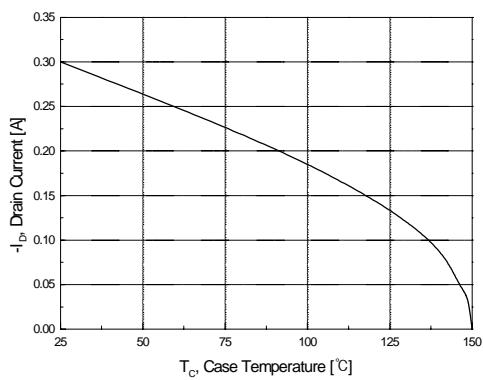


Figure 9. Maximum Safe Operating Area



**Figure 10. Maximum Drain Current
vs. Case Temperature**

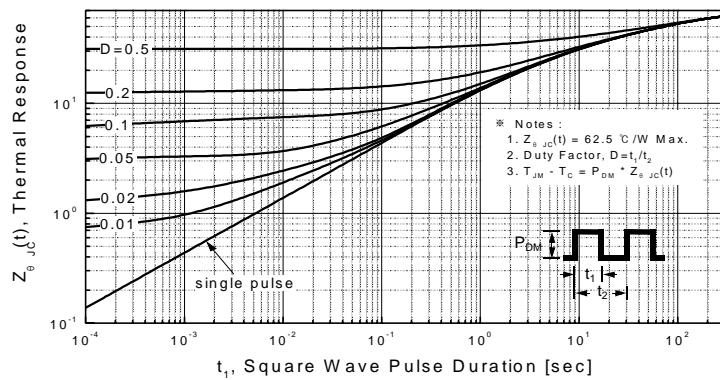
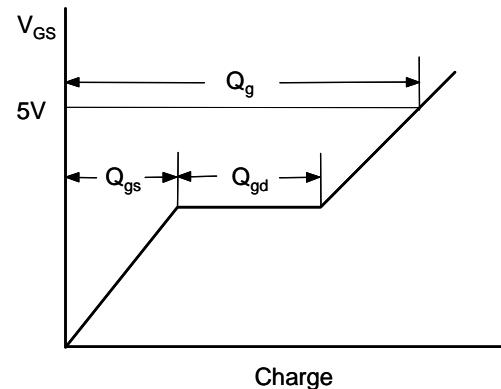
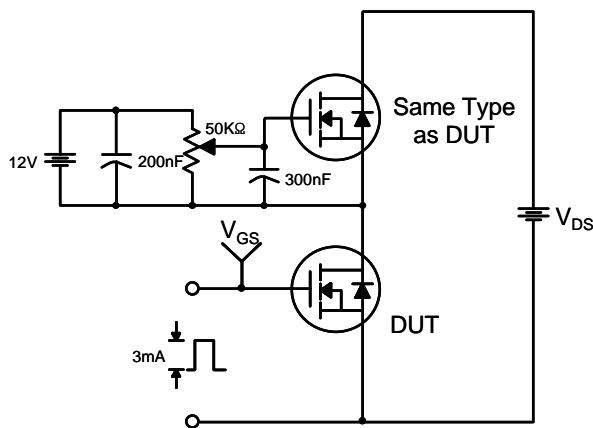
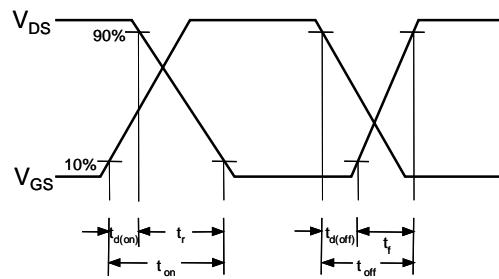
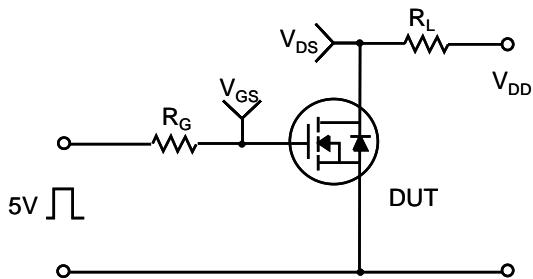


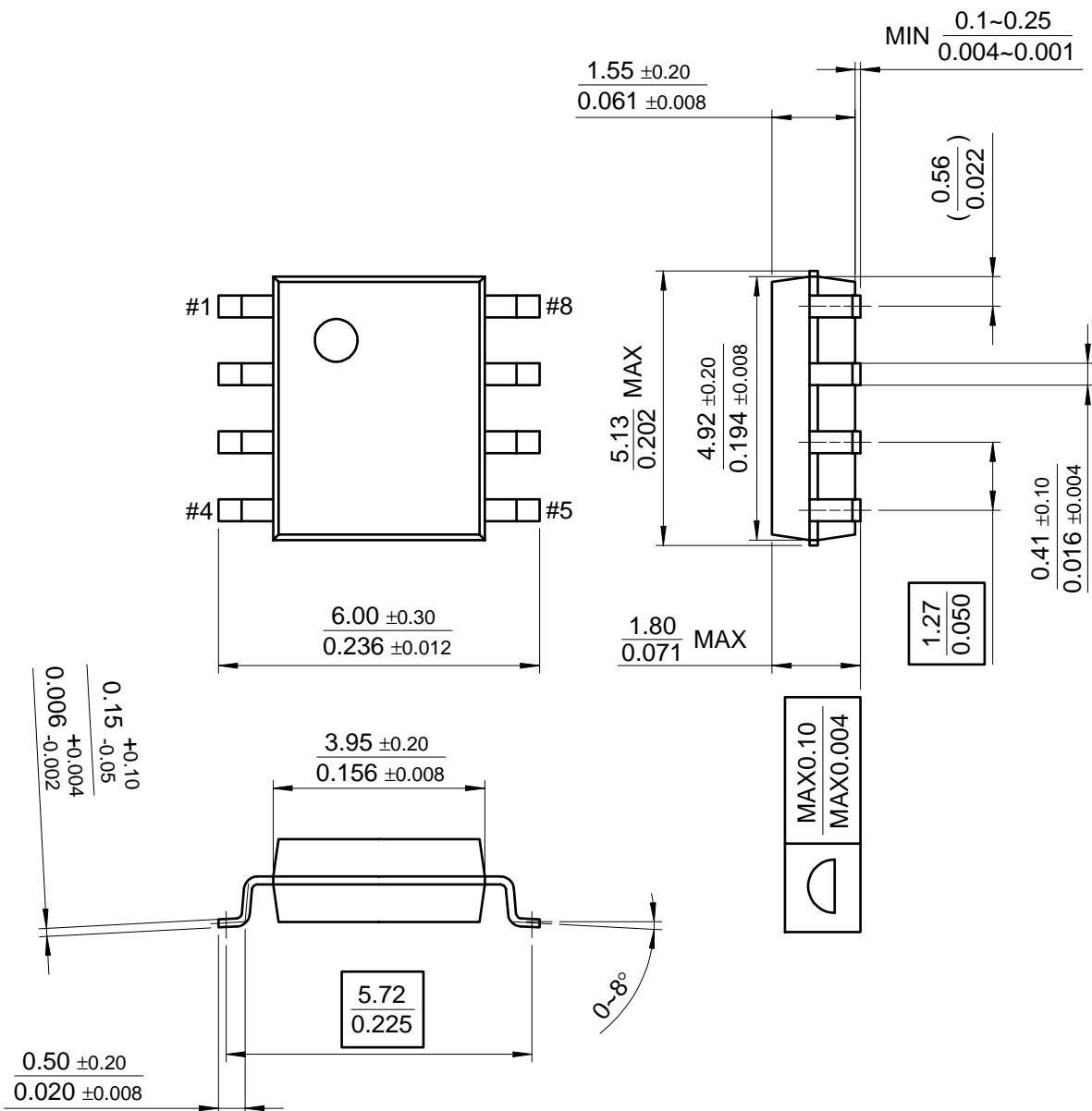
Figure 11. Transient Thermal Response Curve

Gate Charge Test Circuit & Waveform**Resistive Switching Test Circuit & Waveforms**

FQSS4900

Package Dimensions

8-SOP



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FQS4900
 Dual N-Channel 60V & P-Channel 300V
 QFET

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status/pricing/packaging](#)

General description

These N and P-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for low voltage applications such as high efficiency switching DC/DC converters, and DC motor control.

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Features

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 $R_{DS(on)} = 0.55\Omega$ @ $V_{GS} = 10\text{ V}$
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 (typical N-Channel 1.6 nC)
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Product status/pricing/packaging

Product	Product status	Pricing*	Package type	Leads	Packing method
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* 1,000 piece Budgetary Pricing

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